APPROVAL SHEET

RFBLN 2012 (0805) Series – RoHS Compliance

MULTILAYER CERAMIC BALUN TRANSFORMER

Halogens Free Product

5 GHz ISM Band Working Frequency

Balanced/ Unbalanced Port - 50Ω / 50Ω

P/N: RFBLN2012090K0T

*Contents in this sheet are subject to change without prior notice

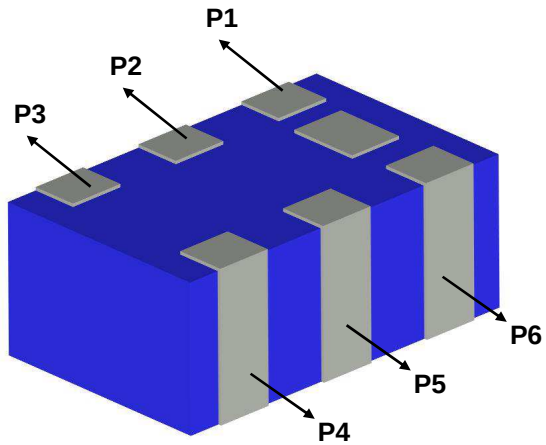
FEATURES

1. Multilayer LTCC (Low Temperature Cofired Ceramics) Technology
2. Miniatured Size 2.00 x 1.25 x 0.95 mm^3
3. Low Insertion Loss reduces power consumption
4. Low inband Amplitude and Phase imbalance enable high performance wireless system operation.
5. Suitable for 5GHz Working Frequency Operation
6. Special Balance/ Unbalance impedance is upon requested.

APPLICATIONS

1. IEEE 802.11a Wireless LAN Application
2. ETSI/BRAN HiperLan/2 Application

CONSTRUCTION



PIN	Definition	PIN	Definition
P1	Unbalance Port	**P4**	Balance Port
P2	GND	**P5**	GND
P3	Balance Port	**P6**	NC

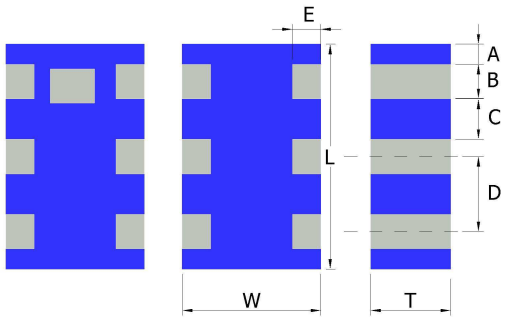
Fig 1. Outline and Pin arrangement of 5GHz Balun

DESCRIPTION

The new ceramic balun transformer developed by Walsin Technology Corporation is specifically designed for 5 GHz ISM band applications, as shown in Fig. 1. Today, the 5GHz ISM band allocations include USA U-NII band (5.150GHz~ 5.825GHz), Europe HiperLan and ISM (5.150GHz~5.875GHz), Japan (4.90GHz~5.10GHz), and IEEE802.11a WLAN (5.150GHz~5.825GHz). Our 5GHz ceramic balun is tailored to deliver superior in-band and out-band frequency performance. It has low amplitude imbalance and phase imbalance, wide bandwidth (-10dB), and low insertion loss characteristics. With Walsin's advanced LTCC (Low Temperature Co-fired Ceramic) manufacturing technology and 3D EM Simulation product design tools, we guarantee the quality of our products.

The dimension of our rectangular-shaped ceramic balun is 2.00 x 1.25 x 0.95 mm^3. This compact size fits the surface mount automation technology and miniaturization trends for modern portable/mobile devices.

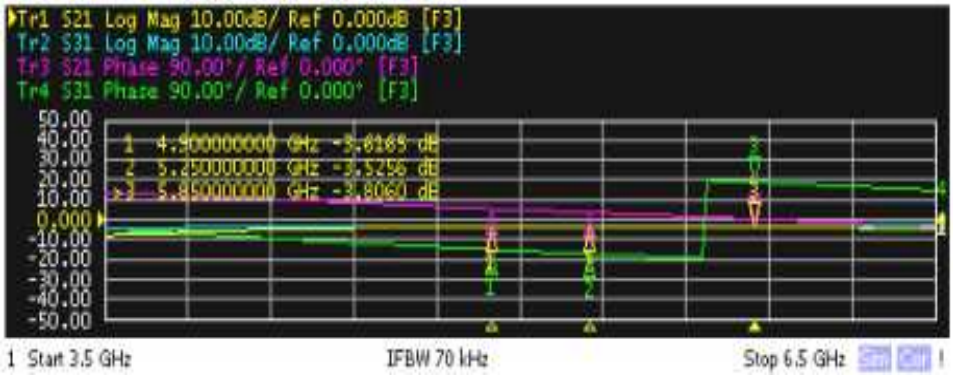
DIMENSIONS

Figure	Symbol	Dimension
	L	2.00 ± 0.15 mm
	W	1.25 ± 0.15 mm
	T	0.95 ± 0.10 mm
	A	0.20 ± 0.20 mm
	B	0.30 ± 0.20 mm
	C	0.35 ± 0.20 mm
	D	0.65 ± 0.20 mm
	E	0.30 ± 0.20 mm

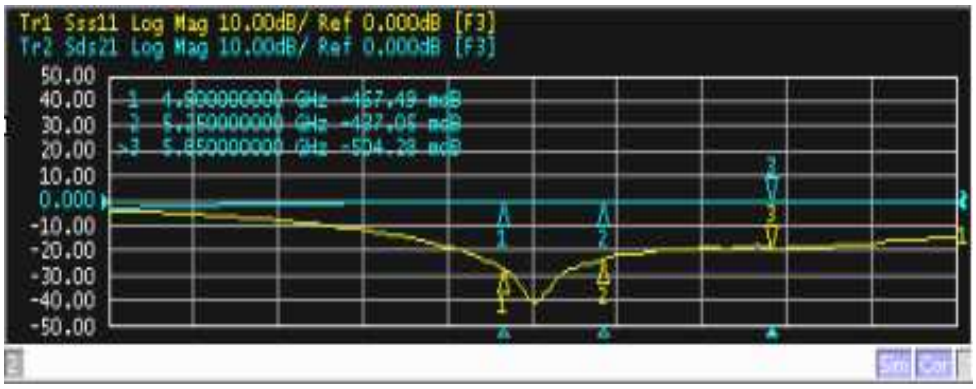
ELECTRICAL CHARACTERISTICS

RFBLN2012090K0T	Specification
Frequency range	5400 ± 500 MHz
Insertion Loss (dB)	1.1
Impedance (Ω) Unbalanced	50
Impedance (Ω) Balanced	50
Return Loss (dB) Min.	10
Amplitude Balance (dB)	2.0
Phase Balance (degree)	180° ± 10°
Operation Temperature Range	-40°C ~ +85°C
Typical Electrical Chart	

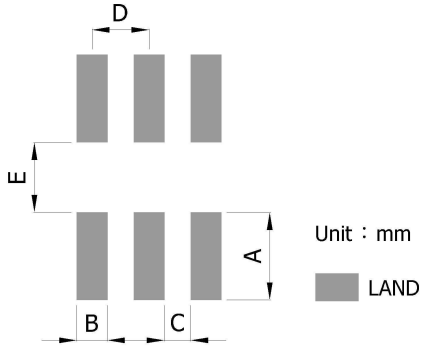
(1) Amplitude balance and Phase balance



(2)Insertion Loss



SOLDER LAND PATTERN

Figure	Symbol	Dimension (mm)
	A	1.00 ± 0.10
	B	0.35 ± 0.10
	C	0.30 ± 0.10
	D	0.65 ± 0.10
	E	0.80 ± 0.10
Line width to be design to match 50Ω characteristic impedance, depending on PCB material and thickness		

RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6 JESD22-B102D	*Solder bath temperature：235 ± 5°C *Immersion time：2 ± 0.5 sec *Solder：Sn3Ag0.5Cu for lead-free	At least 95% of a surface of each terminal electrode must be covered by fresh solder.
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature：260 ± 5°C *Leaching immersion time：30 ± 0.5 sec *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature：120~150℃, 1 minute. *Solder temperature：270±5°C *Immersion time：10±1 sec *Solder：Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test. Loss of metallization on the edges of each electrode shall not exceed 25%.
Drop Test JIS C 0044	*Height：75 cm *Test Surface：Rigid surface of concrete or steel. *Times：6 surfaces for each units；2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force： 5N(≦0603)；10N(>0603) *Test time：10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Samples shall satisfy electrical specification after test.

Temperature cycle JIS C 0025	1. 30±3 minutes at -40°C±3°C, 2. 10~15 minutes at room temperature, 3. 30±3 minutes at +85°C±3°C, 4. 10~15 minutes at room temperature, Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test.
Vibration JIS C 0040	*Frequency：10Hz~55Hz~10Hz(1min) *Total amplitude：1.5mm *Test times：6hrs.(Two hrs each in three mutually perpendicular directions)	No mechanical damage. Samples shall satisfy electrical specification after test.
High temperature JIS C 0021	*Temperature：85°C±2°C *Test duration：1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test.
Humidity (steady conditions) JIS C 0022	*Humidity：90% to 95% R.H. *Temperature：40±2°C *Time：1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs ※ 500hrs measuring the first data then 1000hrs data	No mechanical damage. Samples shall satisfy electrical specification after test.
Low temperature JIS C 0020	*Temperature：-40°C±2°C *Test duration：1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test.

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

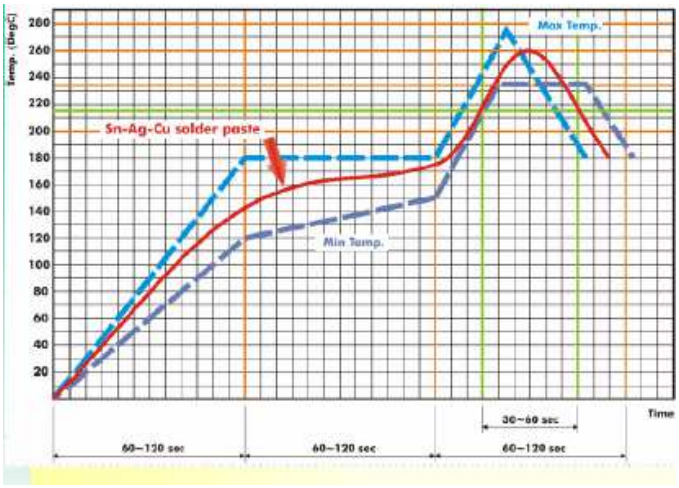


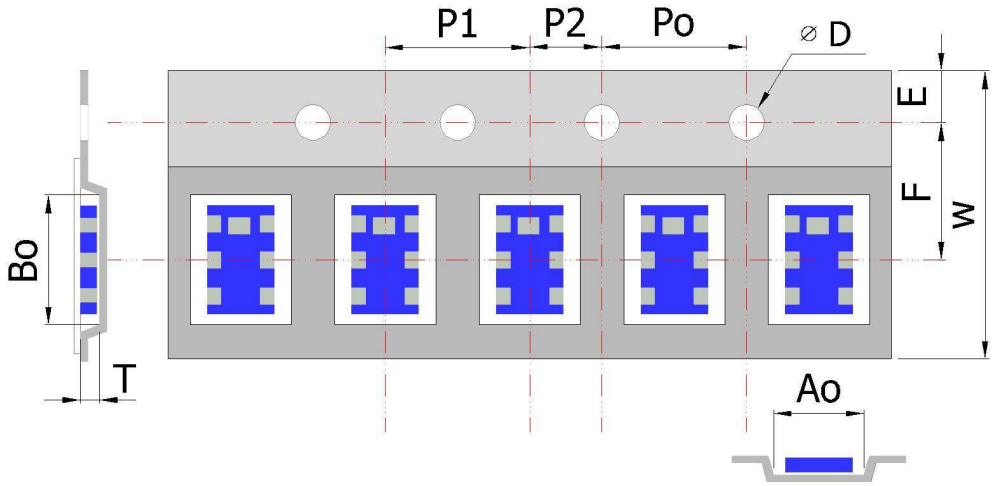
Fig 2. Infrared soldering profile

ORDERING CODE

RF	BLN	201209	0	K	0	T
Walsin RF device	**Product Code** BLN : BALUN	**Dimension code** Per 2 digits of Length, Width, Thickness : e.g. : 201209 = Length 20, Width 12, Thickness 09	**Unit of dimension** 0 : 0.1 mm 1 : 1.0 mm	**Application** K: ISM 5.2/5.8 Dual Band	**Specification** Design Code X = **0**: 50/ **50** X = **1**: 50/ **100** X = **2**: 50/ **200**	**Packing** T : 7" Reeled

Minimum Ordering Quantity: 2000 pcs per reel.

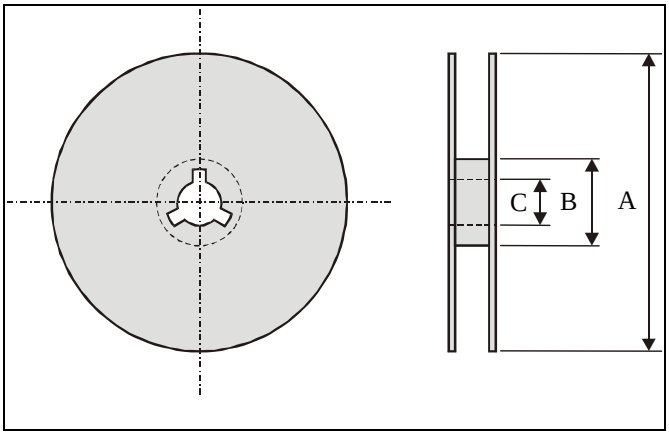
PACKAGING



Plastic Tape specifications (unit :mm)

Index	Ao	Bo	ΦD	T	W
Dimension (mm)	1.52 ± 0.10	2.35 ± 0.10	1.55 ± 0.10	1.12 ± 0.10	8.0 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05

Reel dimensions



Index	A	B	C
Dimension (mm)	Φ178	Φ60.0	Φ13.5

Typing Quantity: 2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

(1) Aircraft equipment

(2) Aerospace equipment

(3) Undersea equipment

(4) Medical equipment

(5) Disaster prevention / crime prevention equipment

(6) Traffic signal equipment

(7) Transportation equipment (vehicles, trains, ships, etc.)

(8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

(1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.

(2) Storage environment condition.

- Products should be storage in the warehouse on the following conditions.
- Temperature : -10 to +40°C
- Humidity : 30 to 70% relative humidity
- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.